Title (en)

MOLDING FLASK MADE OF THERMOPLASTIC RESIN

Title (de)

AUS THERMOPLASTISCHEM HARZ HERGESTELLTER FORMKASTEN

Title (fr)

CHASSIS DE MOULAGE EN RESINE THERMOPLASTIQUE

Publication

EP 1728942 A4 20081119 (EN)

Application

EP 04799687 A 20041108

Priority

- JP 2004016906 W 20041108
- JP 2004092741 A 20040326

Abstract (en)

[origin: EP1728942A1] A form 10 for constructing a concrete structure is formed of a thermoplastic resin containing an inorganic material, and includes a first main plate 11 facing a poured concrete, a second main plate 12 opposing this first main plate, and partition plates 15, 16 extending between these first and second main plates. The partition plates 15 construct a plurality of first reinforcement parts 30 having at least one kind of cross sectional shape selected from an approximately rectangular shape and an approximately truss shape in a width direction from right to left. And the partition plates 16 construct a second reinforcement part 31 having an approximately rectangular cross sectional shape of a width capable of supporting an outer edge of a head part 51 of a nail 50 at a portion 52 where a columnar reinforcement body 40 for supporting a form is to be nailed.

IPC 8 full level

E04G 9/05 (2006.01); **E04B 2/86** (2006.01)

CPC (source: EP US)

E04G 9/05 (2013.01 - EP US)

Citation (search report)

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Designated contracting state (EPC)

ES

DOCDB simple family (publication)

EP 1728942 A1 20061206; **EP 1728942 A4 20081119**; CN 100473795 C 20090401; CN 1926293 A 20070307; HK 1103113 A1 20071214; US 2007200050 A1 20070830; WO 2005093189 A1 20051006

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